

SCES395B-JULY 2002-REVISED OCTOBER 2005

#### **FEATURES**

- Member of the Texas Instruments Widebus™
  Family
- DOC<sup>™</sup> Circuitry Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I $_{\rm OH}$  and I $_{\rm OL}$  of  $\pm$ 24 mA at 2.5-V V $_{\rm CC}$
- Control Inputs V<sub>IH</sub>/V<sub>IL</sub> Levels Are Referenced to V<sub>CCA</sub> Voltage
- If Either V<sub>CC</sub> Input Is at GND, Both Ports Are in the High-Impedance State

- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over the Full 1.4-V to 3.6-V Power-Supply Range
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

#### **DESCRIPTION/ORDERING INFORMATION**

This 16-bit (dual-octal) noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track  $V_{CCA}$ .  $V_{CCA}$  accepts any supply voltage from 1.4 V to 3.6 V. The B port is designed to track  $V_{CCB}$ .  $V_{CCB}$  accepts any supply voltage from 1.4 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVCA164245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the outputs so the buses are effectively isolated.

The SN74AVCA164245 is designed so that the control pins (1DIR, 2DIR,  $1\overline{OE}$ , and  $2\overline{OE}$ ) are supplied by  $V_{CCA}$ .

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CCA}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. If either  $V_{CC}$  input is at GND, then both ports are in the high-impedance state.

#### ORDERING INFORMATION

T <sub>A</sub>	PACKA	GE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	TSSOP - DGG	Tape and reel	SN74AVCA164245GR	AVCA164245
40°C to 95°C	TVSOP – DGV	Tape and reel	SN74AVCA164245VR	WA4245
−40°C to 85°C	VFBGA – GQL	Tape and reel	SN74AVCA164245KR	WA 424E
	VFBGA – ZQL	Tape and reel	74AVCA164245ZQLR	WA4245

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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## **TERMINAL ASSIGNMENTS**

## **DGG OR DGV PACKAGE** (TOP VIEW) 48 10E



**GQL OR ZQL PACKAGE** (TOP VIEW)

1 2 3 4 5 6 000000 Α 000000 В 000000 С 000000 D  $\bigcirc$  $\bigcirc$ Е OO $\bigcirc$ F 000000 G 000000 Н 000000 J 000000 Κ

#### TERMINAL ASSIGNMENTS<sup>(1)</sup>

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1 <del>OE</del>
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	V <sub>CCB</sub>	$V_{CCA}$	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	V <sub>CCB</sub>	$V_{CCA}$	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 <del>OE</del>

(1) NC - No internal connection

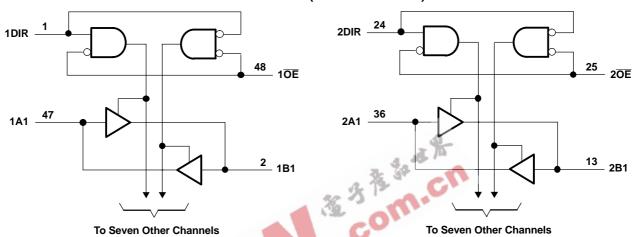


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# FUNCTION TABLE (EACH 8-BIT SECTION)

INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

### **LOGIC DIAGRAM (POSITIVE LOGIC)**



Pin numbers shown are for the DGG and DGV packages.



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## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CCA} \ V_{CCB}$	Supply voltage range		-0.5	4.6	V
		I/O ports (A port)	-0.5	4.6	
$V_{I}$	Input voltage range (2)	I/O ports (B port)	-0.5	4.6	V
		Control inputs	-0.5	4.6	
1/	Voltage range applied to any output	A port	-0.5	4.6	V
Vo	in the high-impedance or power-off state (2)	B port	-0.5	4.6	V
1/	Voltage range applied to any output in the high or law state (2)(3)	A port	-0.5	V <sub>CCA</sub> + 0.5	V
Vo	Voltage range applied to any output in the high or low state (2)(3)	B port	-0.5	V <sub>CCB</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
lo	Continuous output current			±50	mA
	Continuous current through V <sub>CCA</sub> , V <sub>CCB</sub> , or GND			±100	mA
		DGG package		70	
$\theta_{JA}$	Package thermal impedance (4)	DGV package		58	°C/W
		GQL/ZQL package		42	
T <sub>stg</sub>	Storage temperature range	373	-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating" conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

 <sup>(2)</sup> The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 (3) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
 (4) The package thermal impedance is calculated in accordance with JESD 51-7.



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## Recommended Operating Conditions (1)(2)(3)

			V <sub>CCI</sub>	V <sub>cco</sub>	MIN	MAX	UNIT
V <sub>CCA</sub>	Supply voltage				1.4	3.6	V
V <sub>CCB</sub>	Supply voltage				1.4	3.6	V
			1.4 V to 1.95 V		V <sub>CCI</sub> × 0.65		
$V_{IH}$	High-level input voltage	Data inputs	1.95 V to 2.7 V		1.7		V
	input voltage		2.7 V to 3.6 V		2		
			1.4 V to 1.95 V			$V_{CCI} \times 0.35$	
$V_{IL}$	Low-level input voltage	Data inputs	1.95 V to 2.7 V			0.7	V
	input voltage		2.7 V to 3.6 V			0.8	
			1.4 V to 1.95 V		$V_{CCA} \times 0.65$		
$V_{IH}$	High-level input voltage	Control inputs (referenced to V <sub>CCA</sub> )	1.95 V to 2.7 V		1.7		V
	input voltage	(referenced to VCCA)	2.7 V to 3.6 V		2		
			1.4 V to 1.95 V			$V_{CCA} \times 0.35$	
$V_{IL}$	Low-level input voltage	Control inputs (referenced to V <sub>CCA</sub> )	1.95 V to 2.7 V			0.7	V
	input voltage	(referenced to v CCA)	2.7 V to 3.6 V			0.8	
VI	Input voltage	'		4	0	3.6	V
.,	0	Active state		4.15.14	0	V <sub>cco</sub>	.,
Vo	Output voltage	3-state		18 3º	0	3.6	V
		'	33	1.4 V to 1.6 V		-2	
	LPale lavel systems of an		135	1.65 V to 1.95 V		-4	4
I <sub>OH</sub>	High-level output cu	irrent		2.3 V to 2.7 V		-8	mA
				3 V to 3.6 V		-12	
				1.4 V to 1.6 V		2	
	Landanal and and			1.65 V to 1.95 V		4	1
I <sub>OL</sub>	Low-level output cu	rrent		2.3 V to 2.7 V		8	mA
	\			3 V to 3.6 V		12	
Δt/Δν	Input transition rise	or fall rate				5	ns/V
T <sub>A</sub>	Operating free-air to	emperature			-40	85	°C

V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.
 V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.
 All unused data inputs of the device must be held at V<sub>CCI</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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## Electrical Characteristics (1)(2)

over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CON	DITIONS	V <sub>CCA</sub>	OOA OOB		TYP(3)	MAX	UNIT
		$I_{OH} = -100 \mu A$ ,	$V_I = V_{IH}$	1.4 V to 3.6 V	1.4 V to 3.6 V	V <sub>CCO</sub> - 0.2			
		$I_{OH} = -2 \text{ mA},$	$V_I = V_{IH}$	1.4 V	1.4 V	1.05			
$V_{OH}$		$I_{OH} = -4 \text{ mA},$	$V_I = V_{IH}$	1.65 V	1.65 V	1.2			V
		$I_{OH} = -8 \text{ mA},$	$V_I = V_{IH}$	2.3 V	2.3 V	1.75			
		$I_{OH} = -12 \text{ mA},$	$V_I = V_{IH}$	3 V	3 V	2.3			
		$I_{OH} = 100 \mu A$ ,	$V_I = V_{IL}$	1.4 V to 3.6 V	1.4 V to 3.6 V			0.2	
		$I_{OH} = 2 \text{ mA},$	$V_I = V_{IL}$	1.4 V	1.4 V			0.35	
$V_{OL}$		$I_{OH} = 4 \text{ mA},$	$V_I = V_{IL}$	1.65 V	1.65 V			0.45	V
		$I_{OH} = 8 \text{ mA},$	$V_I = V_{IL}$	2.3 V	2.3 V			0.55	
		$I_{OH} = 12 \text{ mA},$	$V_I = V_{IL}$	3 V	3 V			0.7	
l <sub>l</sub>	Control inputs	$V_I = V_{CCA}$ or GND		1.4 V to 3.6 V	3.6 V			±2.5	μΑ
ı	A port	$V_{1}$ or $V_{0} = 0$ to 3.6 V		0 V	0 to 3.6 V			±10	μΑ
off	B port	$v_1 \text{ or } v_0 = 0 \text{ to 3.6 V}$		0 to 3.6 V	0 V 🚜			±10	μА
	A or B port	., ., .,	OE = V <sub>IH</sub>	3.6 V	3.6 V			±12.5	
oz <sup>(4)</sup>	B port	$V_O = V_{CCO}$ or GND, $V_I = V_{IH}$ or $V_{IL}$	OE = don't care	0 V	<b>3</b> .6 V			±12.5	μΑ
	A port	11 11H 21 11E	OL = doint care	3.6 V	0 V			±12.5	
				1.6 V	1.6 V			20	
				1.95 V	1.95 V			20	
l		$V_I = V_{CCI}$ or GND,	$I_{O} = 0$	2.7 V	2.7 V			30	μΑ
CCA		VI = VCCI OI GIVD,	10 - 0	0 V	3.6 V			-40	μΛ
				3.6 V	0 V			40	
				3.6 V	3.6 V			40	
				1.6 V	1.6 V			20	
				1.95 V	1.95 V			20	
		$V_I = V_{CCI}$ or GND,	I <sub>O</sub> = 0	2.7 V	2.7 V			30	μΑ
ССВ		vi = vcci or ordo,	10 = 0	0 V	3.6 V			40	μΑ
				3.6 V	0 V			-40	
				3.6 V	3.6 V			40	
C <sub>i</sub>	Control inputs	V <sub>I</sub> = 3.3 V or GND		3.3 V	3.3 V		4		pF
C <sub>io</sub>	A or B port	$V_O = 3.3 \text{ V or GND}$		3.3 V	3.3 V		5		pF

 $<sup>\</sup>begin{array}{ll} \text{(1)} & V_{CCO} \text{ is the } V_{CC} \text{ associated with the output port.} \\ \text{(2)} & V_{CCI} \text{ is the } V_{CC} \text{ associated with the input port.} \\ \text{(3)} & \text{All typical values are at } T_A = 25^{\circ}\text{C.} \\ \text{(4)} & \text{For I/O ports, the parameter } I_{OZ} \text{ includes the input leakage current.} \\ \end{array}$ 



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### **Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CCA}$  = 1.5 V  $\pm$  0.1 V (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TO V <sub>CCB</sub> = 1.5 V ± 0.1 V		V <sub>CCB</sub> = 1.8 V ± 0.15 V		V <sub>CCB</sub> = 2.5 V ± 0.2 V		V <sub>CCB</sub> = 3.3 V ± 0.3 V		UNIT
	(INPOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Α	В	1.7	6.7	1.9	6.3	1.8	5.5	1.7	5.8	20
t <sub>pd</sub>	В	Α	1.8	6.8	2.2	7.4	2.1	7.6	2.1	7.3	ns
	ŌĒ	Α	2.6	8.4	2.7	8.2	2.3	6.3	2.1	5.6	50
t <sub>en</sub>	OE	В	2.7	8.6	3.2	10.2	3.2	10.8	3.2	10.7	ns
4	ŌĒ	Α	2.1	7	2.5	7	1.7	5.3	2	6.1	20
t <sub>dis</sub>	OE	В	2.1	7.1	2.5	7.1	2.1	6.5	2.1	6.4	ns

### **Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$  (see Figure 2)

PARAMETER	FROM	TO (OUTPUT)	V <sub>CCB</sub> = ± 0.7	1.5 V 1 V	V <sub>CCB</sub> = 1 ± 0.15	V 8.1	V <sub>CCB</sub> = ± 0.2		V <sub>CCB</sub> = ± 0.3	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
4	Α	В	1.7	6.4	1.8	6	1.7	4.7	1.6	4.3	no
t <sub>pd</sub>	В	Α	1.4	5.5	1.8	6	1.8	5.8	1.8	5.5	ns
	ŌĒ	Α	2.5	8	2.7	7.8	2.2	5.8	2	5.1	20
t <sub>en</sub>	OE	В	1.8	6.7	2.7	7.8	2.7	8.1	2.7	8.1	ns
	ŌĒ	A	2.1	6.4	<b>2</b> .5	6.4	1.5	4.5	1.8	5	20
t <sub>dis</sub>	OE .	В	2.1	6.6	2.5	6.4	2	5.5	2	5.5	ns

## **Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CCA}$  = 2.5 V  $\pm$  0.2 V (see Figure 2)

PARAMETER	FROM (INPUT)	TO	V <sub>CCB</sub> = 1.5 V ± 0.1 V		V <sub>CCB</sub> = 1.8 V ± 0.15 V		V <sub>CCB</sub> = 2.5 V ± 0.2 V		V <sub>CCB</sub> = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
4	A	В	1.6	6	1.8	5.6	1.5	4	1.4	3.4	20
t <sub>pd</sub>	В	Α	1.3	4.6	1.7	4.4	1.5	4	1.4	3.7	ns
4	ŌĒ	Α	2.6	7.4	2.7	7.2	2.2	5.3	2	4.5	20
t <sub>en</sub>	OE	В	1.2	4.1	2.2	5.1	2.2	5.3	2.2	5.3	ns
	ŌĒ	Α	2	5.7	2.3	5.7	1.4	3.7	1.6	4	50
t <sub>dis</sub>	OE .	В	0.9	4.5	1.7	4.5	1.4	3.7	1.4	3.7	ns



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#### **Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CCA}$  = 3.3 V  $\pm$  0.3 V (see Figure 2)

PARAMETER	FROM	TO	V <sub>CCB</sub> = ± 0.1		V <sub>CCB</sub> = ± 0.1		V <sub>CCB</sub> = ± 0.2		V <sub>CCB</sub> = ± 0.3	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
4	Α	В	1.5	5.9	1.7	5.4	1.5	3.7	1.4	3.1	20
t <sub>pd</sub>	В	Α	1.3	4.5	1.6	3.8	1.5	3.3	1.4	3.1	ns
	ŌĒ	Α	2.5	7	2.6	6.9	2.1	5	1.9	4.1	20
t <sub>en</sub>	OE	В	0.8	2.6	1.9	4	2	4.1	1.9	4.1	ns
•	ŌĒ	Α	1.2	5.4	2.2	5.2	1.2	3.3	1.5	3.6	ne
t <sub>dis</sub>	OE	В	1.2	5.4	1.7	4.4	1.5	3.6	1.5	3.6	ns

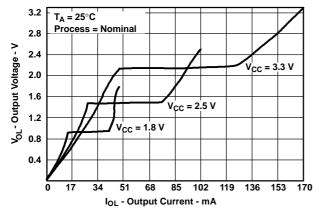
#### **Operating Characteristics**

 $V_{CCA}$  and  $V_{CCB}$  = 3.3 V,  $T_A$  = 25°C

	PARAMETER		TEST C	ONDITIONS	TYP	UNIT
	Power dissipation capacitance per transceiver,	Outputs enabled			14	
	A-port input, B-port output	Outputs disabled	0	f 10 MHz	7	~F
C <sub>pdA</sub>	Power dissipation capacitance per transceiver,	Outputs enabled	$C_L = 0$ ,	f = 10 MHz	20	pF
	B-port input, A-port output	Outputs disabled	1 .		7	
	Power dissipation capacitance per transceiver,	Outputs enabled			14	
	A-port input, B-port output	Outputs disabled	0 0	f 40 MH-	7	C
C <sub>pdB</sub>	Power dissipation capacitance per transceiver,	Outputs enabled	$C_L = 0$ ,	f = 10 MHz	20	pF
	B-port input, A-port output	Outputs disabled		•	7	

#### **OUTPUT DESCRIPTION**

The DOC<sup>TM</sup> circuitry is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical  $V_{OL}$  vs  $I_{OL}$  and  $V_{OH}$  vs  $I_{OH}$  curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOC<sup>TM</sup>) Circuitry Technology and Applications*, literature number SCEA009.



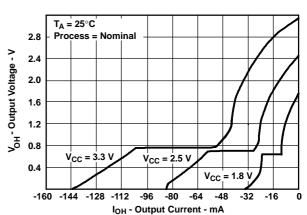
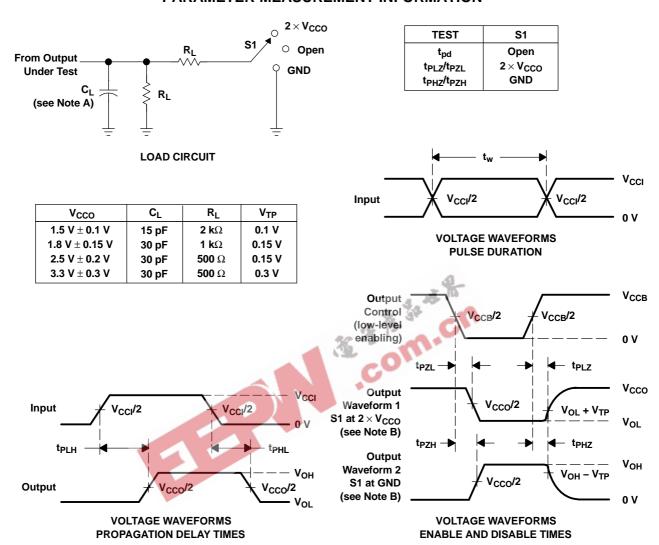


Figure 1. Output Voltage vs Output Current



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#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C<sub>I</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $dv/dt \geq$  1 V/ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
  - H. V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.
  - I.  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.

Figure 2. Load Circuit and Voltage Waveforms



#### PACKAGE OPTION ADDENDUM

18-Jul-2006

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp (3)
74AVCA164245GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVCA164245GRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVCA164245VRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVCA164245ZQLR	ACTIVE	BGA MI CROSTA R JUNI OR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM
SN74AVCA164245GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVCA164245KR	ACTIVE	BGA MI CROSTA R JUNI OR	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74AVCA164245VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

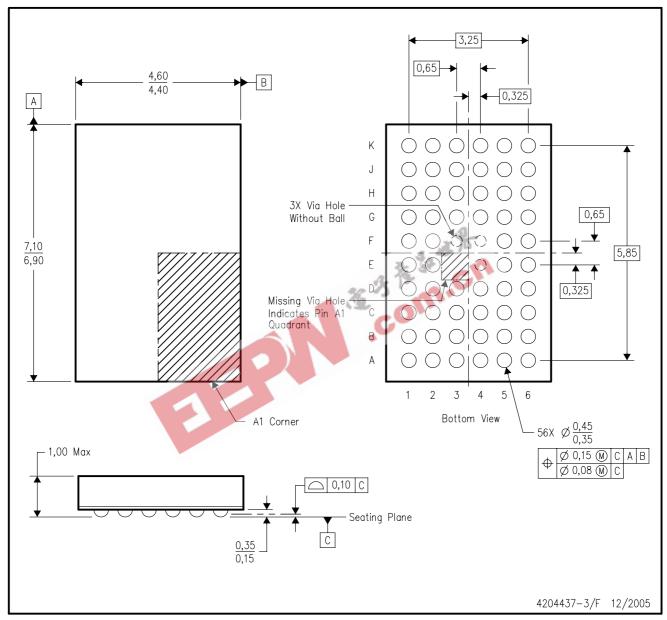
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## ZQL (R-PBGA-N56)

## PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

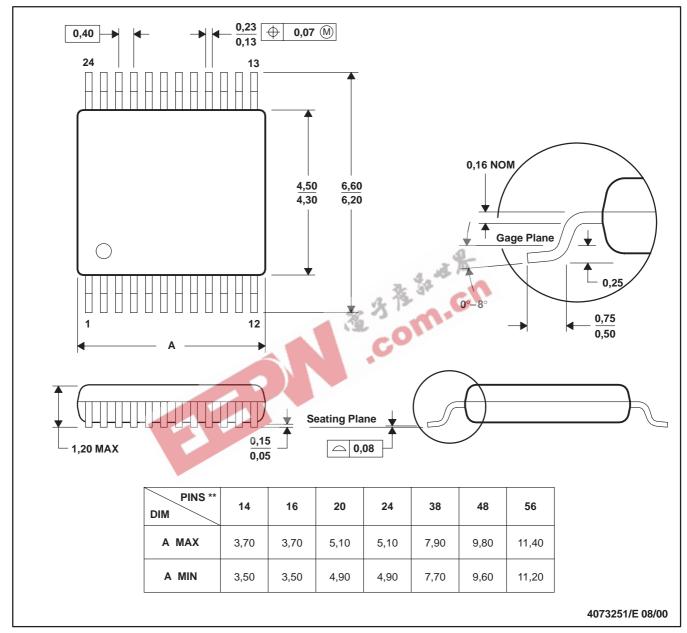
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).



### DGV (R-PDSO-G\*\*)

#### **24 PINS SHOWN**

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

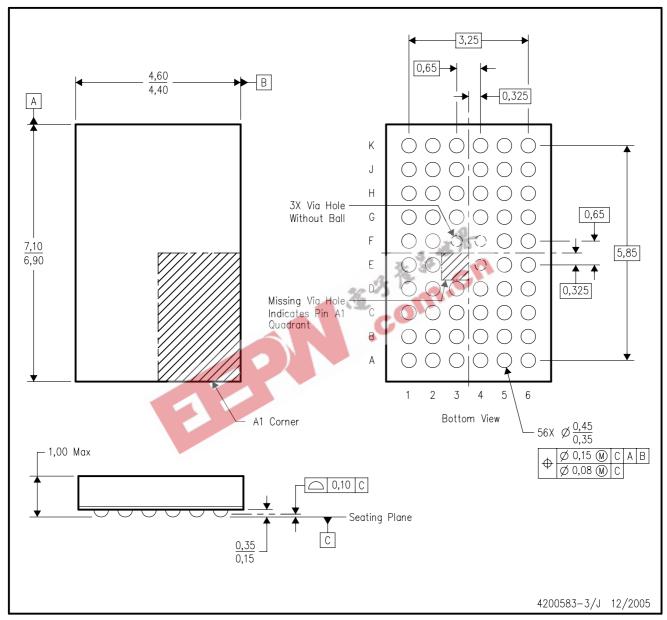
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



## GQL (R-PBGA-N56)

## PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

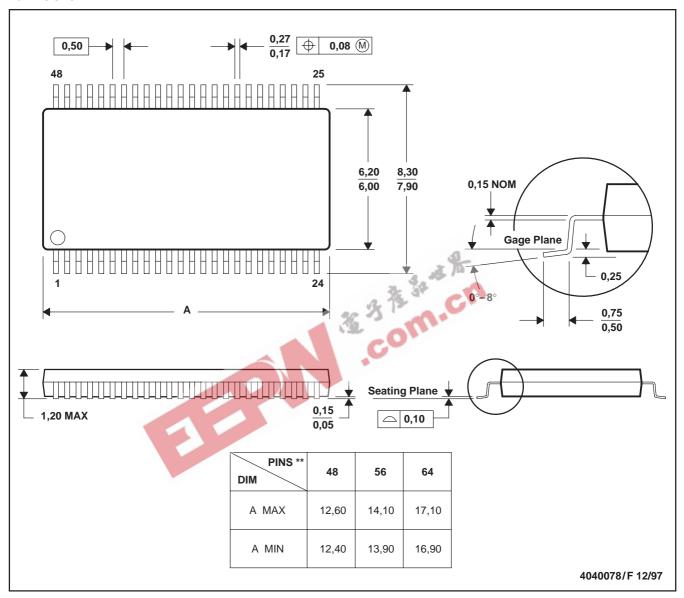
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



### DGG (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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